

Rev.G Apr.-2018

TO-263

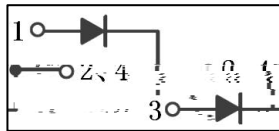
Schottky Diode in a TO-263 Plastic Package.

Low forward voltage drop, low power losses, High efficiency operation.

OR-ing

DC-DC

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.



PIN1 Anode

PIN 2 4 Cathode

PIN 3 Anode

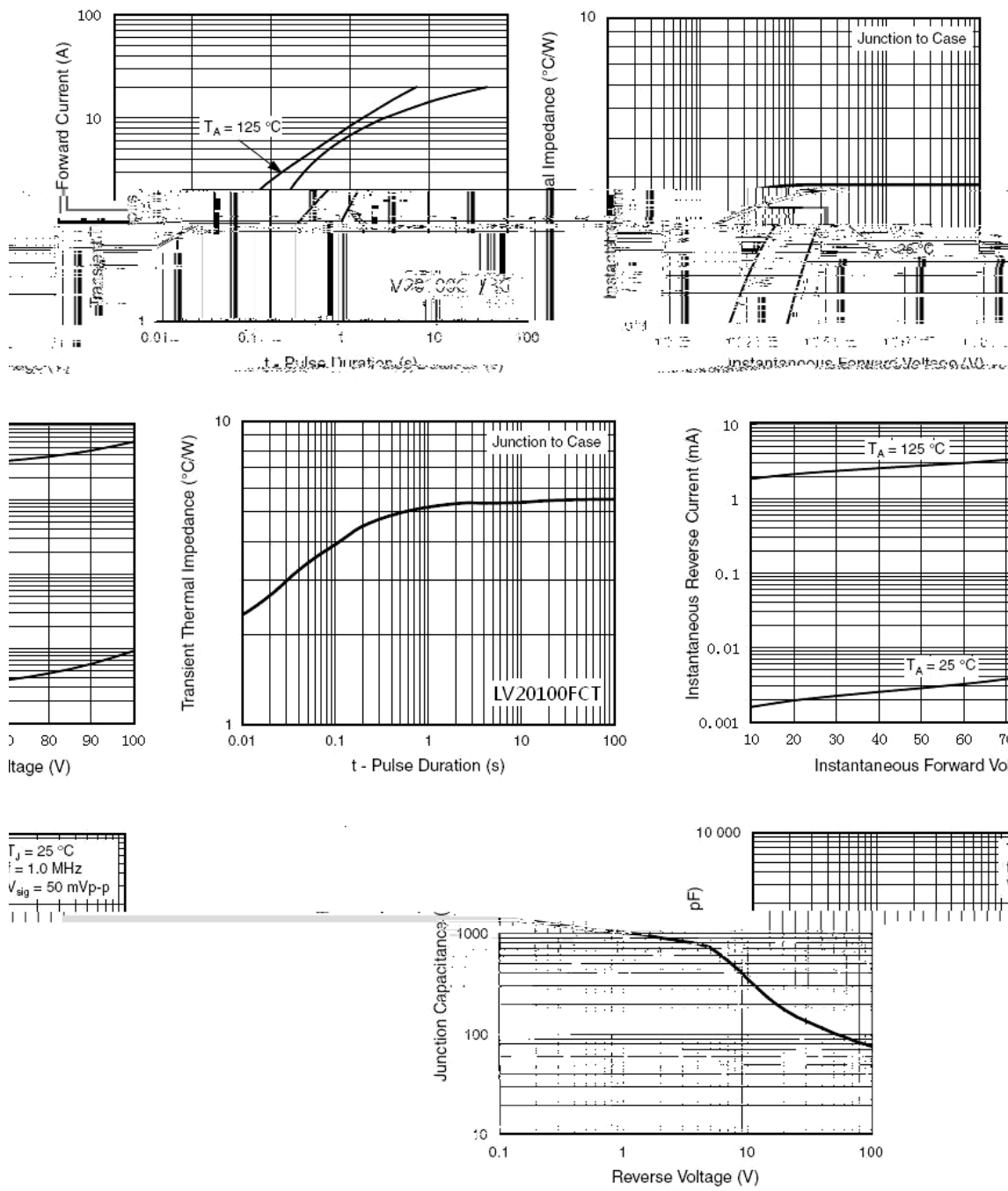
See Marking Instructions.

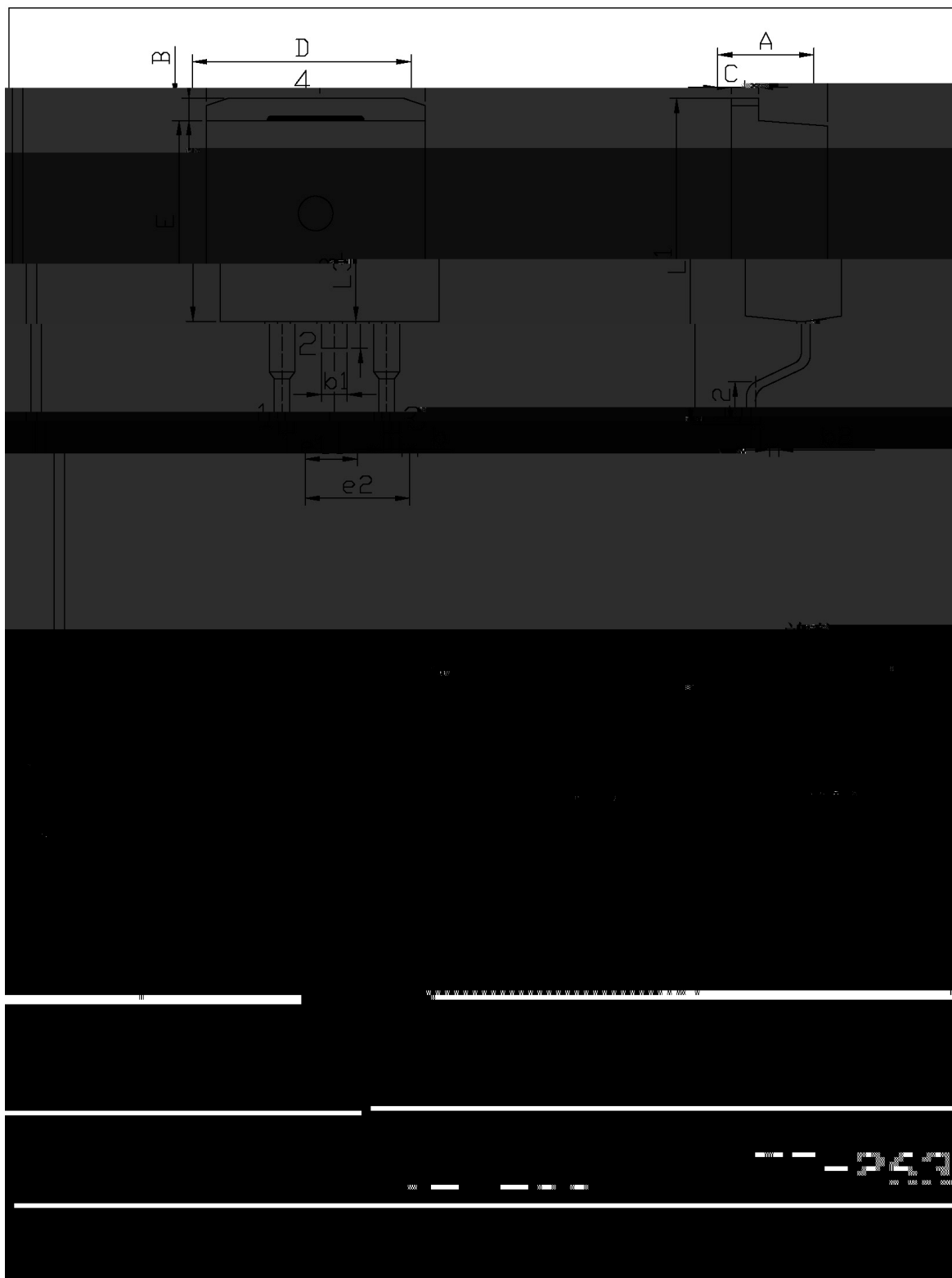
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	100	V
Average forward rectified Current	I_F	2X10	A
Non Repetitive Peak Surge Current	I_{FSM}	150	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	2.8	/W
Junction and Storage Temperature Range	$T_j T_{stg}$	-40~+150	

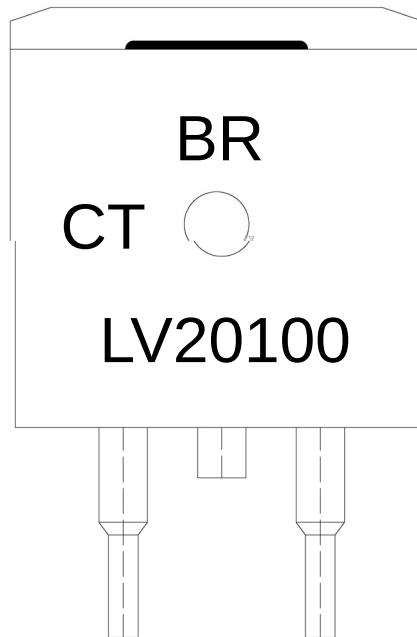
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$	$I_R=1mA$ $T_a=25$	100			V
Forward Voltage	V_{FM}	$I_F=5.0A$ $T_a=25$		0.55	0.65	V
		$I_F=10A$ $T_a=25$		0.73	0.79	V
		$I_F=5A$ $T_a=125$		0.50	0.60	V
		$I_F=10A$ $T_a=125$		0.62	0.68	V
Instantaneous Reverse Current	I_R Note 1	$V_R=100V$ $T_a=25$			100	μA
		$V_R=100V$ $T_a=125$		10	25	mA

/Notes

1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip







BR

LV20100

CT:

Note:

BR:

Company Code

LV20100

Product Type.

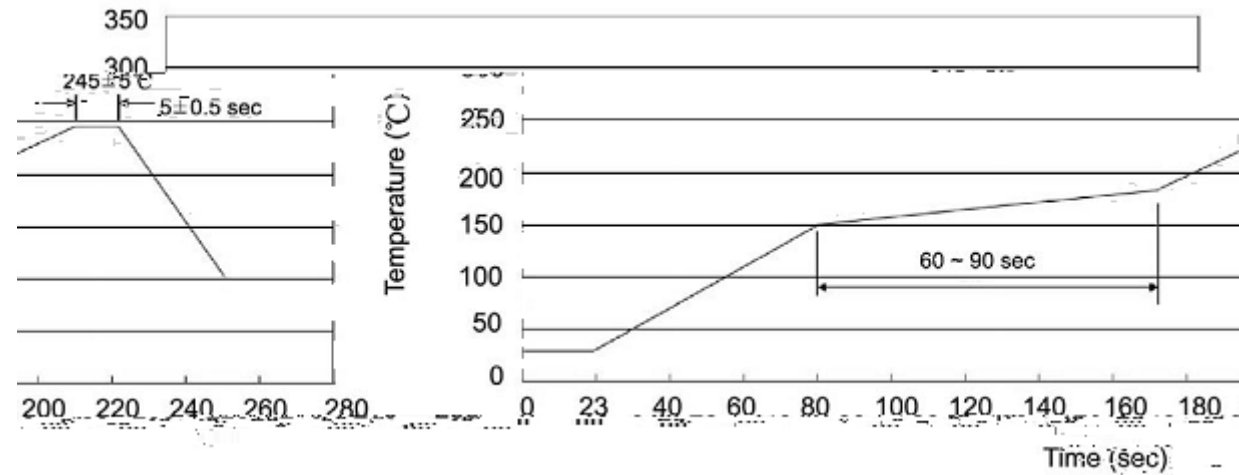
CT:

Internal Structure

****:

Lot No. Code, code change with Lot No.

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;

1.Preheating:25~150 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱